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(54) Title: COMPONENT SUCTION METHOD

(57) Abstract

The method includes feeding component (8) accommodated in component storage spaces (9c) of a tape base (9a) to a predetermined position, lowering a nozzle (7) capable of sucking the component supplied to the predetermined position, stopping the nozzle (7) with a predetermined distance from an upper surface of the tape base, pushing an undersurface of the component up when the nozzle is at a bottom dead center or a position adjacent to the center, vacuum-sucking the component by the nozzle at the bottom dead center or the position adjacent to the center, and moving the component sucked by the nozzle to a predetermined position of a board after the vacuum-sucking. The storage space (9c) or the nozzle (7) has an extra air inlet to improve the suction of the micro component (8).

